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(54) **METHOD FOR BONDING POLYMER FILM TO POLYMER FILM OR INORGANIC MATERIAL SUBSTRATE, POLYMER FILM LAMINATE, AND LAMINATE OF POLYMER FILM AND INORGANIC MATERIAL SUBSTRATE**

VERFAHREN ZUM BINDEN EINES POLYMERFILMS AN EINEN POLYMERFILM ODER AN EIN SUBSTRAT AUS ANORGANISCHEM MATERIAL, POLYMERFILMLAMINAT SOWIE LAMINAT AUS DEM POLYMERFILM UND DEM SUBSTRAT AUS ANORGANISCHEM MATERIAL

PROCÉDÉ DE LIAISON D'UN FILM POLYMÈRE À UN FILM POLYMÈRE OU À UN SUBSTRAT DE MATIÈRE INORGANIQUE, STRATIFIÉ DE FILM POLYMÈRE, ET STRATIFIÉ DE FILM POLYMÈRE ET SUBSTRAT DE MATIÈRE INORGANIQUE

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